

LMC555

CMOS Timer

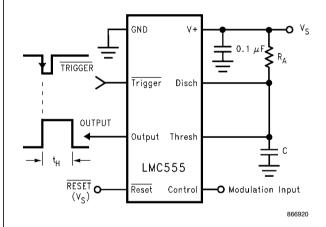
General Description

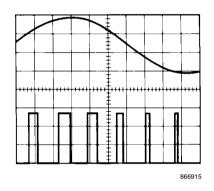
The LMC555 is a CMOS version of the industry standard 555 series general purpose timers. In addition to the standard package (SOIC, MSOP, and MDIP) the LMC555 is also available in a chip sized package (8 Bump micro SMD) using National's micro SMD package technology. The LMC555 offers the same capability of generating accurate time delays and frequencies as the LM555 but with much lower power dissipation and supply current spikes. When operated as a one-shot, the time delay is precisely controlled by a single external resistor and capacitor. In the stable mode the oscillation frequency and duty cycle are accurately set by two external resistors and one capacitor. The use of National Semiconductor's LMCMOS™ process extends both the frequency range and low supply capability.

Features

- Less than 1 mW typical power dissipation at 5V supply
- 3 MHz astable frequency capability
- 1.5V supply operating voltage guaranteed
- Output fully compatible with TTL and CMOS logic at 5V supply
- Tested to -10 mA, +50 mA output current levels
- Reduced supply current spikes during output transitions
- Extremely low reset, trigger, and threshold currents
- Excellent temperature stability
- Pin-for-pin compatible with 555 series of timers
- Available in 8-pin MSOP Package and 8-Bump micro SMD package

Pulse Width Modulator





Ordering Information

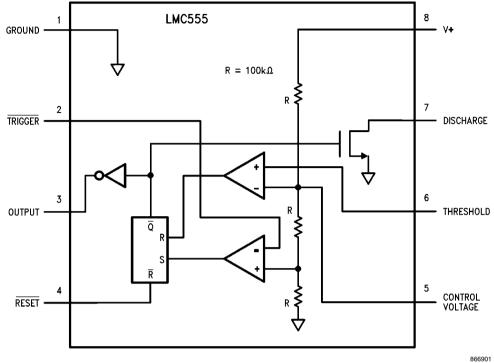
Package	Temperature Range	Package Marking	Transport Media	NSC Drawing	
	Industrial -40°C to +85°C				
8-Pin Small Outline (SO)	LMC555CM	LMC555CM	Rails	M08A	
	LMC555CMX	LIVICOSSCIVI	2.5k Units Tape and Reel	IVIUSA	
8-Pin Mini Small Outline	LMC555CMM	ZC5	1k Units Tape and Reel	MUA08A	
(MSOP)	LMC555CMMX	203	3.5k Units Tape and Reel	WIOAUGA	
8-Pin Molded Dip (MDIP)	LMC555CN	LMC555CN	Rails	N08E	
8-Bump micro SMD	LMC555CTP	F02	250 Units Tape and Reel	TPA08FGA	
NOPB	LMC555CTPX	F02	3k Units Tape and Reel	IFAUOFGA	

Note: See Mil-datasheet MNLMC555-X for specifications on the military device LMC555J/883.

 $LMCMOS^{\intercal M} \ is \ a \ trademark \ of \ National \ Semiconductor \ Corp.$

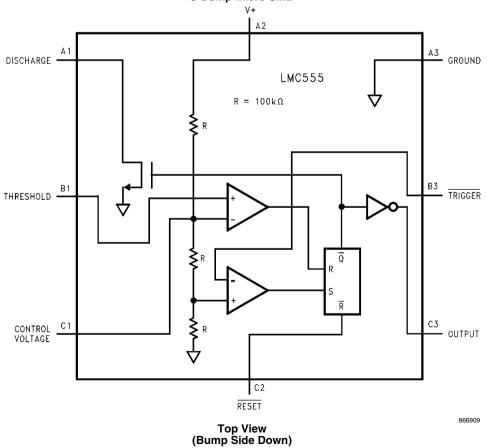
Connection Diagrams

8-Pin SOIC, MSOP, MDIP



Top View

8-Bump micro SMD



Absolute Maximum Ratings (Note 2, Note

3)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage, V+ 15V Input Voltages, V_{TRIG} , V_{RES} , V_{CTRL} , V_{THRESH} -0.3V to V_S + 0.3V

 V_{THRESH} –0.3V to V_{S} + 0.3V Output Voltages, V_{O} , V_{DIS} 15V Output Current I_{O} , I_{DIS} 100 mA

Storage Temperature Range Soldering specification for MDIP package:

Soldering (10 seconds) 260°C

Soldering specification for all other packages: see product folder at www.national.com and www.national.com/ms/MS-MS-SOLDERING.pdf

Operating Ratings (Note 2, Note 3)

Termperature

Range -40°C to +85°C

Thermal Resistance (θ_{1Δ}) (*Note 2*)

SO. 8-Pin Small

Outline 169°C/W

MSOP, 8-Pin Mini

Small Outline 225°C/W

MDIP, 8-Pin

Molded Dip 111°C/W

8-Bump micro

SMD 220°C/W

Maximum Allowable Power Dissipation

@25°C

MDIP-8 1126 mW SO-8 740 mW MSOP-8 555 mW

8 Bump micro

SMD 568 mW

Electrical Characteristics (Note 1, Note 2)

Test Circuit, T = 25°C, all switches open, \overline{RESET} to V_S unless otherwise noted

-65°C to +150°C

Symbol	Parameter	Conditions	Min	Тур	Max	Units (Limits)
l _s	Supply Current	V _S = 1.5V		50	150	
		V _S = 5V		100	250	μA
		V _S = 12V		150	400	
V _{CTRL}	Control Voltage	V _S = 1.5V	0.8	1.0	1.2	
		$V_S = 5V$	2.9	3.3	3.8	V
		V _S = 12V	7.4	8.0	8.6	
V _{DIS}	Discharge Saturation Voltage	V _S = 1.5V, I _{DIS} = 1 mA		75	150	\/
		$V_S = 5V$, $I_{DIS} = 10 \text{ mA}$		150	300	mV
V _{OL}	Output Voltage (Low)	V _S = 1.5V, I _O = 1 mA		0.2	0.4	
		$V_{S} = 5V, I_{O} = 8 \text{ mA}$		0.3	0.6	V
		V _S = 12V, I _O = 50 mA		1.0	2.0	
/ _{OH}	Output Voltage	$V_S = 1.5V, I_O = -0.25 \text{ mA}$	1.0	1.25		
0	(High)	$V_{S} = 5V, I_{O} = -2 \text{ mA}$	4.4	4.7		V
		V _S = 12V, I _O = -10 mA	10.5	11.3		
/ _{TRIG}	Trigger Voltage	V _S = 1.5V	0.4	0.5	0.6	ν,
ma		V _S = 12V	3.7	4.0	4.3	V
TRIG	Trigger Current	V _S = 5V		10		pA
V _{RES}	Reset Voltage	V _S = 1.5V (<i>Note 4</i>)	0.4	0.7	1.0	.,
		V _S = 12V	0.4	0.75	1.1	V
RES	Reset Current	V _S = 5V		10		pA
THRESH	Threshold Current	V _S = 5V		10		pA
DIS	Discharge Leakage	V _S = 12V		1.0	100	nA
	Timing Accuracy	SW 2, 4 Closed				
		V _S = 1.5V	0.9	1.1	1.25	
		V _S = 5V	1.0	1.1	1.20	ms
		V _S = 12V	1.0	1.1	1.25	
Δt/ΔV _S	Timing Shift with Supply	V _S = 5V ± 1V		0.3		%/V
 ∆t/ΔT	Timing Shift with Temperature	V _S = 5V		75		ppm/°C
		–40°C ≤ T ≤ +85°C				

Symbol	Parameter	Conditions	Min	Тур	Max	Units (Limits)
f _A	Astable Frequency	SW 1, 3 Closed, V _S = 12V	4.0	4.8	5.6	kHz
f _{MAX}	Maximum Frequency	Max. Freq. Test Circuit, V _S = 5V		3.0		MHz
t _R , t _F	Output Rise and Fall Times	Max. Freq. Test Circuit $V_S = 5V$, $C_L = 10 pF$		15		ns
t _{PD}	Trigger Propagation Delay	V _S = 5V, Measure Delay from Trigger to Output		100		ns

Note 1: All voltages are measured with respect to the ground pin, unless otherwise specified.

Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

Note 3: See AN-1112 for micro SMD considerations.

Note 4: If the $\overline{\text{RESET}}$ pin is to be used at temperatures of -20°C and below V_S is required to be 2.0V or greater.

Note 5: For device pinout please refer to table 1

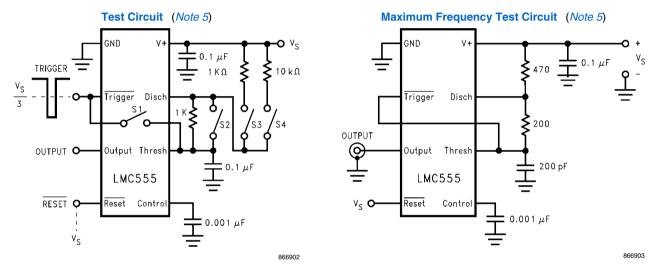


TABLE 1. Package Pinout Names vs. Pin Function

Pin Function	Package Pin numbers		
8-Pin SO, MSOP, and MDIP	8-Bump micro SMD		
GND	1	A3	
Trigger	2	B3	
Output	3	C3	
Reset	4	C2	
Control Voltage	5	C1	
Threshold	6	B1	
Discharge	7	A1	
V+	8	A2	

Application Information

MONOSTABLE OPERATION

In this mode of operation, the timer functions as a one-shot (*Figure 1*). The external capacitor is initially held discharged by internal circuitry. Upon application of a negative trigger pulse of less than $1/3~V_S$ to the $\overline{\text{Trigger}}$ terminal, the flip-flop is set which both releases the short circuit across the capacitor and drives the output high.

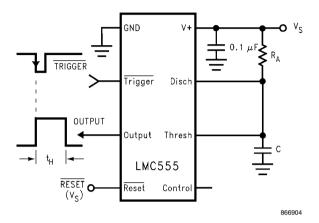
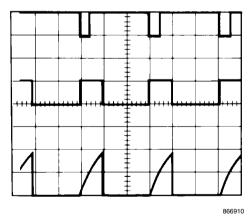


FIGURE 1. Monostable (One-Shot)

The voltage across the capacitor then increases exponentially for a period of $t_H = 1.1~R_AC$, which is also the time that the output stays high, at the end of which time the voltage equals $2/3~V_S$. The comparator then resets the flip-flop which in turn discharges the capacitor and drives the output to its low state. Figure 2 shows the waveforms generated in this mode of operation. Since the charge and the threshold level of the comparator are both directly proportional to supply voltage, the timing internal is independent of supply.



 $V_{\rm CC}$ = 5V Top Trace: Input 5 V/Div.

TIME = 0.1 ms/Div. Middle Trace: Output 5 V/Div. $R_{\rm A}$ = 9.1 k Ω Bottom Trace: Capacitor Voltage 2 V/Div.

C = 0.01 µF

FIGURE 2. Monostable Waveforms

Reset overrides Trigger, which can override threshold. Therefore the trigger pulse must be shorter than the desired $t_{\rm H}$. The minimum pulse width for the Trigger is 20ns, and it is 400ns for the Reset. During the timing cycle when the output is high, the further application of a trigger pulse will not effect the cir-

cuit so long as the trigger input is returned high at least 10µs before the end of the timing interval. However the circuit can be reset during this time by the application of a negative pulse to the reset terminal. The output will then remain in the low state until a trigger pulse is again applied.

When the reset function is not use, it is recommended that it be connected to V_+ to avoid any possibility of false triggering. Figure 3 is a nomograph for easy determination of RC values for various time delays.

Note: In monstable operation, the trigger should be driven high before the end of timing cycle.

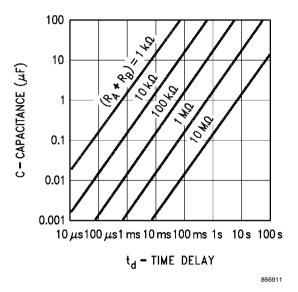


FIGURE 3. Time Delay

ASTABLE OPERATION

If the circuit is connected as shown in Figure 4 (Trigger and Threshold terminals connected together) it will trigger itself and free run as a multivibrator. The external capacitor charges through $R_{\text{A}}+R_{\text{B}}$ and discharges through $R_{\text{B}}.$ Thus the duty cycle may be precisely set by the ratio of these two resistors.

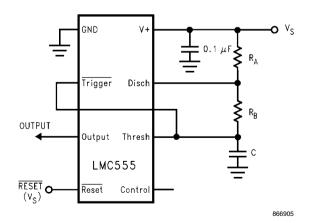
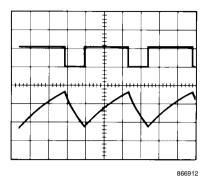


FIGURE 4. Astable (Variable Duty Cycle Oscillator)

In this mode of operation, the capacitor charges and discharges between 1/3 $V_{\rm S}$ and 2/3 $V_{\rm S}$. As in the triggered mode, the charge and discharge times, and therefore the frequency are independent of the supply voltage.

5

Figure 5 shows the waveform generated in this mode of operation.



 $V_{CC} = 5V$ Top Trace: Output 5 V/Div.

TIME = 20 µs/Div. Bottom Trace: Capacitor Voltage 1 V/Div.

 $R_A = 3.9 \text{ k}\Omega$ $R_B = 9 \text{ k}\Omega$ $C = 0.01 \mu\text{F}$

FIGURE 5. Astable Waveforms

The charge time (output high) is given by

$$t_1 = 0.693 (R_A + R_B)C$$

And the discharge time (output low) by:

$$t_2 = 0.693 (R_B)C$$

Thus the total period is:

$$T = t_1 + t_2 = 0.693 (R_A + 2R_B)C$$

The frequency of oscillation is:

$$f = \frac{1}{T} = \frac{1.44}{(R_A + 2\,R_B)\,C}$$

Figure 6 may be used for quick determination of these RC Values. The duty cycle, as a fraction of total period that the output is low, is:

$$D = \frac{R_B}{R_A + 2R_B}$$

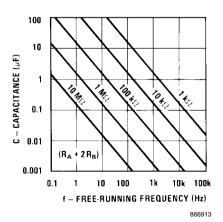
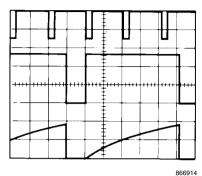


FIGURE 6. Free Running Frequency

FREQUENCY DIVIDER

The monostable circuit of *Figure 1* can be used as a frequency divider by adjusting the length of the timing cycle. *Figure 7* shows the waveforms generated in a divide by three circuit.



 $V_{CC} = 5V$ Top Trace: Input 4 V/Div. TIME = 20 µs/Div. Middle Trace: Output 2 V/Div. $R_A = 9.1 \ k\Omega$ Bottom Trace: Capacitor 2 V/Div.

 $C = 0.01 \mu F$

FIGURE 7. Frequency Divider Waveforms

PULSE WIDTH MODULATOR

When the timer is connected in the monostable mode and triggered with a continuous pulse train, the output pulse width can be modulated by a signal applied to the Control Voltage Terminal. *Figure 8* shows the circuit, and in *Figure 9* are some waveform examples.

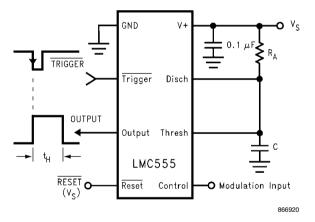
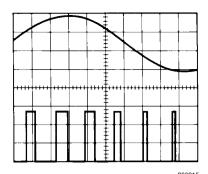


FIGURE 8. Pulse Width Modulator

www.national.com

6



 V_{CC} = 5V Top Trace: Modulation 1 V/Div. TIME = 0.2 ms/Div. Bottom Trace: Output Voltage 2 V/Div. R_A = 9.1 k Ω

FIGURE 9. Pulse Width Modulator Waveforms

PULSE POSITION MODULATOR

 $C = 0.01 \ \mu F$

This application uses the timer connected for astable operation, as in *Figure 10*, with a modulating signal again applied to the control voltage terminal. The pulse position varies with the modulating signal, since the threshold voltage and hence the time delay is varied. *Figure 11* shows the waveforms generated for a triangle wave modulation signal.

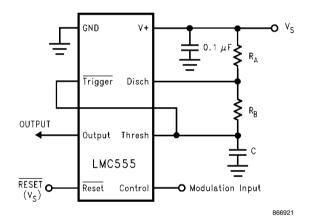
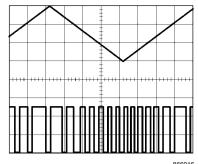


FIGURE 10. Pulse Position Modulator



 V_{CC} = 5V Top Trace: Modulation Input 1 V/Div. TIME = 0.1 ms/Div. Bottom Trace: Output Voltage 2 V/Div. R_A = 3.9 kΩ R_B = 3 kΩ

FIGURE 11. Pulse Position Modulator Waveforms

50% DUTY CYCLE OSCILLATOR

The frequency of oscillation is

 $f = 1/(1.4 R_C C)$

 $C = 0.01 \mu F$

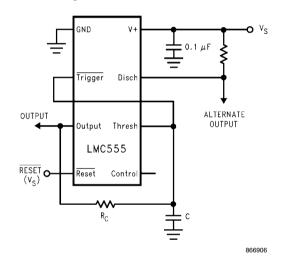
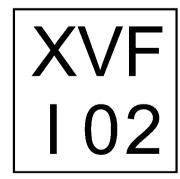


FIGURE 12. 50% Duty Cycle Oscillator

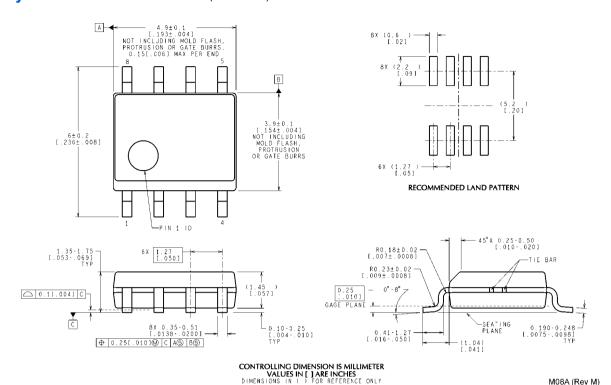
micro SMD Marking Orientation Top View



X = 1 Digit Date Code V = 1 Digit Die Run I = Pin 1 Designator

866926

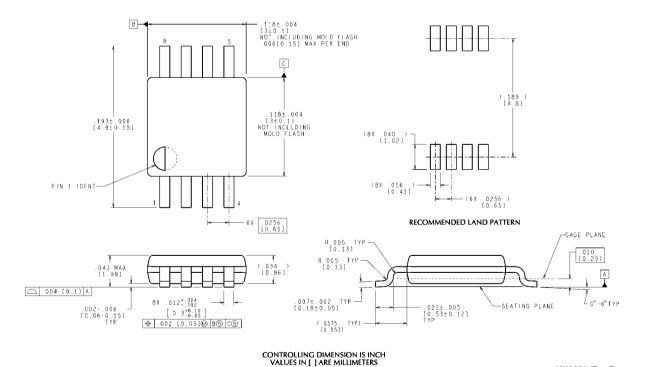
Physical Dimensions inches (millimeters) unless otherwise noted



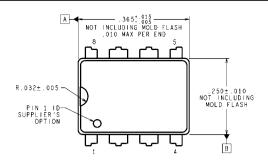
Molded Small Outline (SO) Package (M) **NS Package Number M08A**

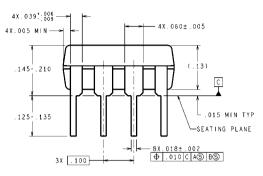
M08A (Rev M)

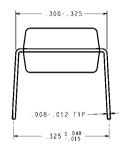
MUA08A (Rev F)



8-Pin (0.118" Wide) Molded Mini Small Outline Package **NS Package Number MUA08A**



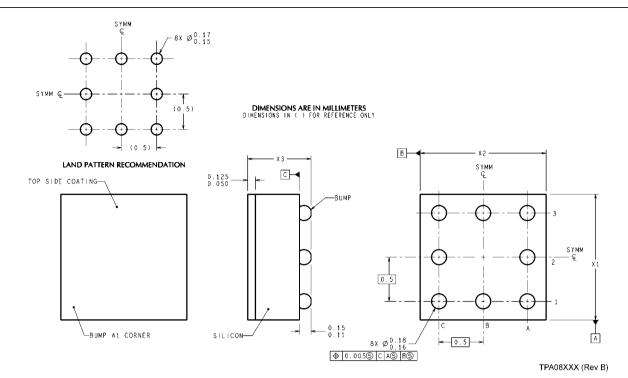




DIMENSIONS ARE IN INCHES
DIMENSIONS IN () FOR REFERENCE ONLY

Molded Dual-in-line Package (N) NS Package Number N08E

N08E (Rev G)



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. EPOXY COATING
- 2. FOR SOLDER BUMP COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- 3. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
- 4. PIN A1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION.
- 5. XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACKAGE HEIGHT.
- 6. REFERENCE JEDEC REGISTRATION MO-211, VARIATION BC.

8-Bump micro SMD Package NS Package Number TPA08FGA $X_1 = 1.412$ $X_2 = 1.438$ $X_3 = 0.500$

Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at:

Pro	oducts	Design Support		
Amplifiers	www.national.com/amplifiers	WEBENCH® Tools	www.national.com/webench	
Audio	www.national.com/audio	App Notes	www.national.com/appnotes	
Clock and Timing	www.national.com/timing	Reference Designs	www.national.com/refdesigns	
Data Converters	www.national.com/adc	Samples	www.national.com/samples	
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards	
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging	
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green	
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts	
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality	
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback	
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy	
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions	
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero	
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic	
PLL/VCO	www.national.com/wireless	PowerWise® Design University	www.national.com/training	

THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.

TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS. PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.

EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.

National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.

Copyright© 2010 National Semiconductor Corporation

For the most current product information visit us at www.national.com



National Semiconductor Americas Technical Support Center Email: support@nsc.com Tel: 1-800-272-9959 National Semiconductor Europe Technical Support Center Email: europe.support@nsc.com National Semiconductor Asia Pacific Technical Support Center Email: ap.support@nsc.com National Semiconductor Japan Technical Support Center Email: ipn.feedback@nsc.com